

LIPPERT Embedded Computers joins FeaturePak Initiative

Leading supplier of modular PC systems and COMs for ruggedized applications supports new embedded I/O module standard

April 28, 2010; Mannheim, GERMANY -- Lippert Embedded Computers, a leading global provider of modular, rugged, high reliable embedded computing solutions for OEM and integrated systems applications, today announced their participation in the FeaturePak™ Initiative. The initiative is driving a market-wide adoption of the FeaturePak Specification (pictured below), which defines tiny, application-oriented I/O expansion modules that snap into a 230-pin MXM socket on single board computers (SBCs), computer-on-module (COM) baseboards, and full-custom electronic circuit boards.

"The FeaturePak I/O expansion standard will ease the development of application-oriented baseboards for various kinds of COMs and SBCs such as CoreExpress®, PC/104, QSeven™, SUMIT and others. Customers only need to take care of the application specific physical interfaces on their base board, while the complex building blocks can easily be placed and replaced", said Markus Friese, product manager at LIPPERT Embedded Computers. "Having the same maximum width of 65 mm as CoreExpress COM standard, which was originated by LIPPERT, customers can design very tiny and flexible systems. Our first product based on the FeaturePak specification will give customers a maximum degree of flexibility and customization. Also we will take good care to ensure the ruggedness of the solution, as this is the key to our customer base."

The FeaturePak host interface consists of PCI Express™, USB, I²C, and several other host-interface signals. To these, FeaturePak modules add up to 100 points of application I/O per module.

"FeaturePak I/O expansion modules satisfy the desire of COM customers to be able to add application-specific capabilities to COM baseboards without adding height to the system," explained Jonathan Miller, founder and president of Diamond Systems Corporation, which originated the FeaturePak standard and the FeaturePak Initiative.

The FeaturePak Initiative is supported by its originator, Diamond Systems Corp., along with FeaturePak Initiative members Connect Tech, Cogent Computer Systems, congatec, Hectronic, IXXAT Automation, Douglas Electronics, Arbor Technology and VIA Technologies, MSC, and LIPPERT Embedded Computers.

About Lippert

LIPPERT Embedded Computers is a leading global provider of modular, rugged, high quality, embedded computing solutions for OEMs and systems integrators. LIPPERT's mission is to provide time saving solutions for embedded systems designers to accelerate the product deployment process. Supporting a broad range of open embedded standards such as several PC/104 family derivatives, COM-Express and mini-ITX, LIPPERT also invented the latest small form factor embedded standard CoreExpress. With a strong focus on developing and specifying their products for extreme temperature and shock environments, LIPPERT enables customers to obtain all the benefits of an off-the-shelf CPU solution even in uncommon applications. The company is headquartered in Mannheim, Germany. Customers in the USA and Canada are supported by a sales office in Atlanta, Georgia.

For more information visit

LIPPERT Embedded Computers www.lippertembedded.com
FeaturePak™ Initiative www.featurepak.org
CoreExpress® www.sff-sig.org/coreexpress.html

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